



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s)	Wang	Examiner:	Warren, Matthew E.
Serial No.:	10/736,486	Group Art Unit:	2815
Confirmation No.:	1290	Docket:	669-77 CON/CIP
Filed:	December 15, 2003	Dated:	March 23, 2005
For:	HIGH DENSITY INTEGRATED CIRCUITS AND THE METHOD OF PACKAGING THE SAME		

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

*I hereby certify this correspondence is being deposited with the United States Postal Service as first class mail, postpaid in an envelope, addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450*

By: M.J. Mullin  
M.J. Mullin

**AMENDMENT AND RESPONSE PURSUANT TO 37 C.F.R. §1.111**

Sir:

In response to the non-final Office Action mailed October 5, 2004, a reply to which is being filed today, March 23, 2005, with a three-month extension of time, please consider the claims of the above-identified application in view of the following remarks.

**Amendments to the Claims** are reflected in the listing of the claims which begins on page 2 of this paper.

Remarks begin on page 12 of this paper.